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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

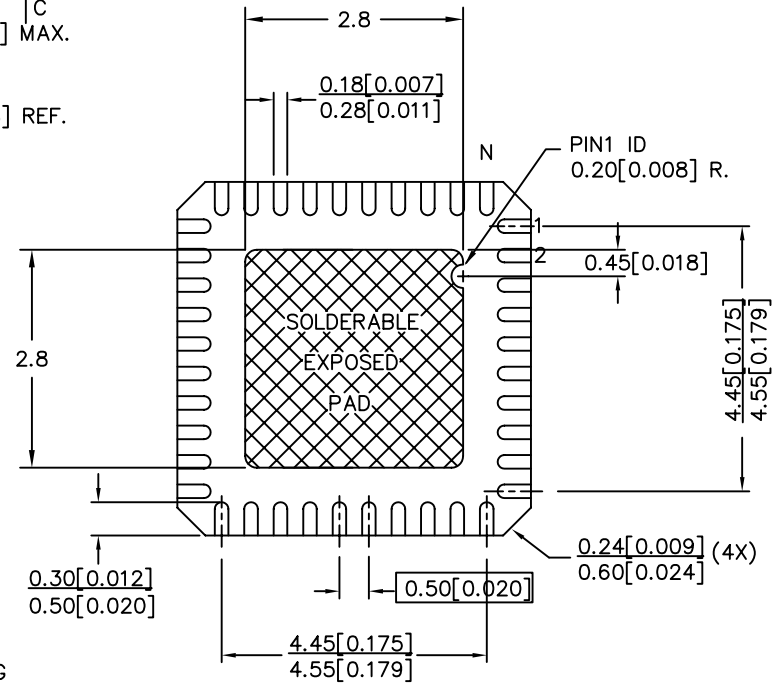
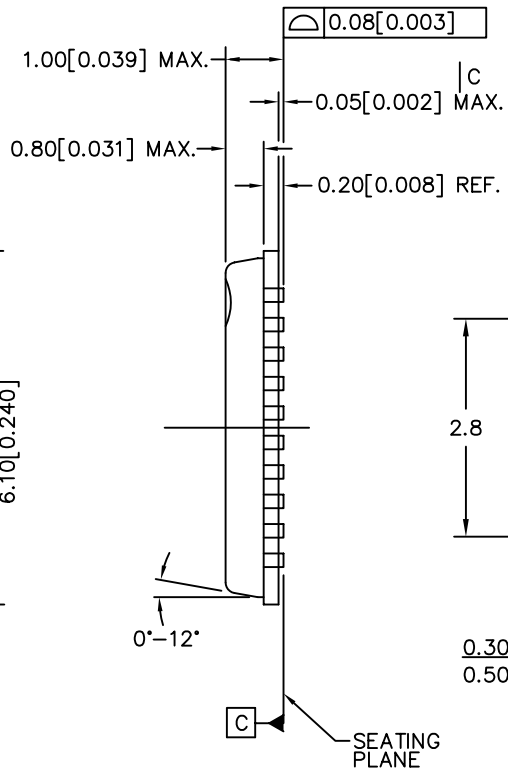
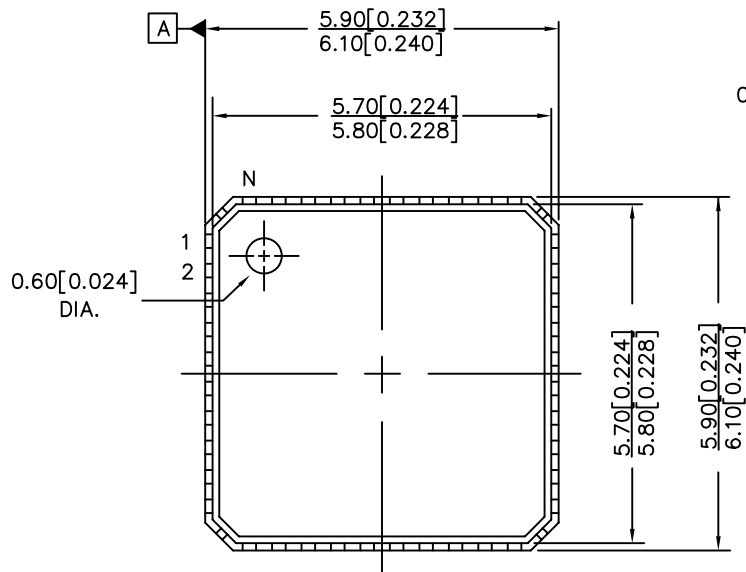
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	127977	NEW RELEASE	06/24/03	N/A
1	-	*A	736321	REVISED DRAWING, DEFINED SOLDERABLE EXPOSED AREA CHANGED SPEC. TITLE, CORRECTED EPAD DIMENSION.	01/29/07	JSO
1	-	*B	2808704	Changed Template and Title from 40LD QFN 6 X 6MM PACKAGE OUTLINE (SUBCON PUNCH TYPE PKG with 2.8 X 2.8 EPAD) to PACKAGE OUTLINE, 40LD QFN 6X6X1.0 MM LY40/LF40 2.8X2.8 EPAD (SUBCON PUNCH TYPE PKG).	11/18/09	QAD
1	-	*C	3352935	Update spec for sunset review, no changed	08/24/11	QAD
1	-	*D	3726162	Changed package weight reference from 0.086g to *refer to PMDD spec	08/28/12	QAD


TOP VIEW

SIDE VIEW

BOTTOM VIEW



NOTES:

-  HATCH IS SOLDERABLE EXPOSED AREA
- REFERENCE JEDEC#: MO-220
- PACKAGE WEIGHT: REFER TO PMDD SPEC.
- ALL DIMENSIONS ARE IN MM [MIN/MAX]
- PACKAGE CODE

PART #	DESCRIPTION
LY40	PB-FREE
LF40	STANDARD

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY JSO	DATE 06/24/03
	DRAWN BY JSO	DATE 06/24/03
	CHECKED BY XANC	DATE 08/28/12
	APPROVED BY QAD	DATE 08/28/12
MATERIAL N/A	APPROVED BY EDCA	DATE 08/28/12
FINISH N/A	APPROVED BY IRB	DATE 08/28/12



TITLE PACKAGE OUTLINE, 40LD QFN 6X6X1.0 MM LY40/LF40 2.8X2.8 EPAD (SUBCON PUNCH TYPE PKG)			
SIZE A	PART NO. LY40/LF40	DWG NO 51-85190	REV *D
SCALED TO FIT	N/A	SHEET 1	OF 1

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